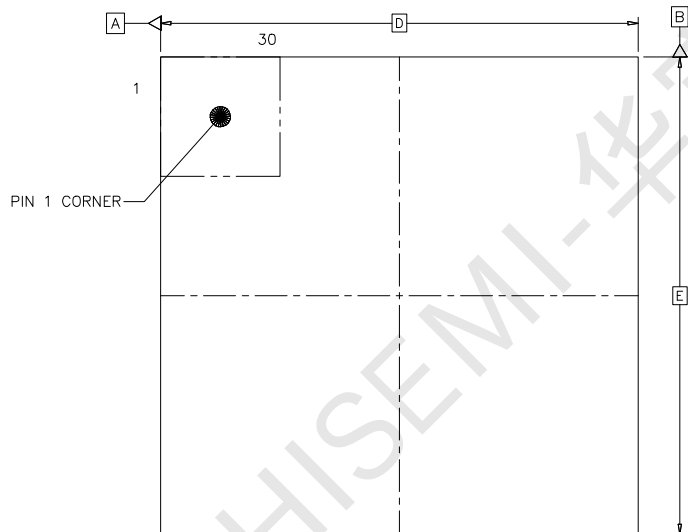
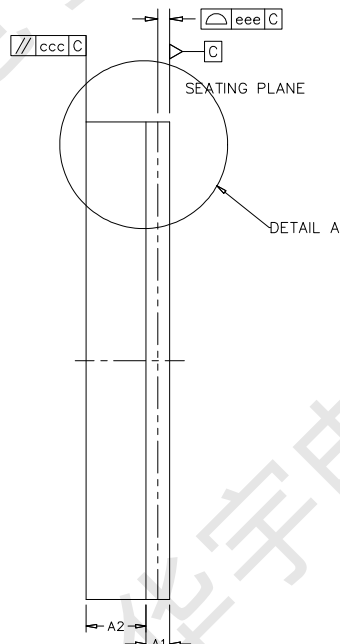


ROHS



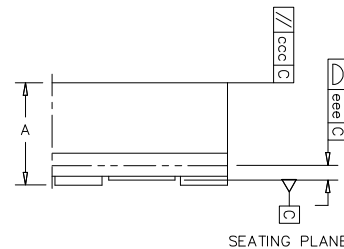
TOP VIEW



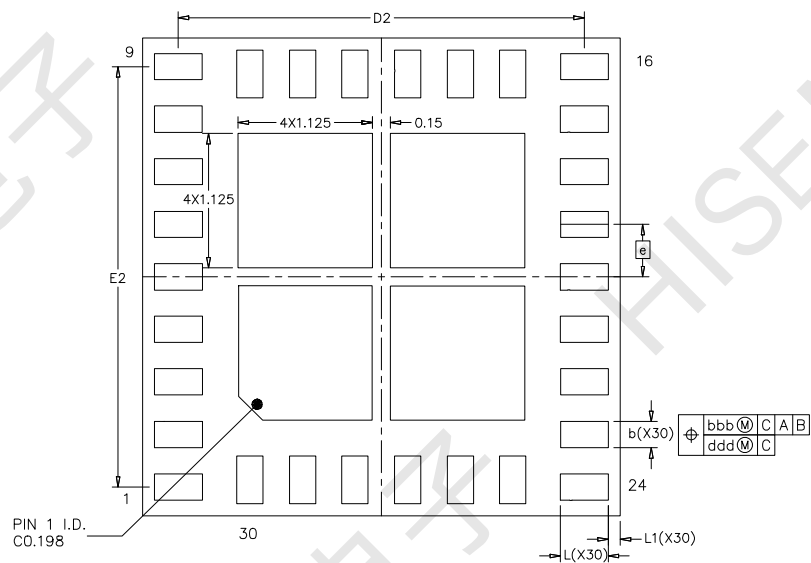
SIDE VIEW

		SYMBOL	MIN	NOM	MAX
TOTAL THICKNESS		A	0.65	0.7	0.75
MOLD CAP		A2	---	0.50	---
SUBSTRATE THICKNESS		A1	0.17	0.2	0.23
LEAD WIDTH		b	0.17	0.22	0.27
BODY SIZE	X	D	3.9	4	4.1
	Y	E	3.9	4	4.1
LEAD PITCH		e	0.44 BSC		
EDGE PAD CENTER TO CENTER		D2	3.4 BSC		
		E2	3.52 BSC		
LEAD LENGTH		L	0.35	0.40	0.45
LEAD TIP TO PKG EDGE		L1	0.025	0.1	0.175
PACKAGE EDGE TOLERANCE		aaa	0.1		
MOLD FLATNESS		ccc	0.1		
COPLANARITY		eee	0.08		
LEAD OFFSET		bbb	0.1		
		ddd	0.08		

Notes.
1. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES;
2. DIMENSIONS AND TOLERANCE CONFORM TO ASME Y14.5-2009;



DETAIL A



BOTTOM VIEW

履历			
序号	内容	版本	日期
1	新发行	A.0	25.6.11

 池州华宇电子科技有限公司 CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD				制图: Draw	NINGLIN 2025.6.13
HY-POD-LGA0076				制图核查: Drawing review	
PACKAGE OUTLINE DIMENSIONS LGA41L (4.0×6.8×0.94-P0.43)				审核: Checker	
页数 page	单位 unit	比例 scale	视图 view	核准: Approved	
1	mm	1:1			